

## **Quarterly Reliability Monitoring Results**

## Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number BAS40L Part Description										
								Nexperia DHAM Schottky				
								MCD package				
		Test Conditions	Duration	# Lots	# Quantity	# Rejects						
			TEST									
			Pre- and Post-Stress									
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below						
		JESD22-A113										
		Bake Tamb = 125 °C	24 hours									
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours									
# A1	Preconditioning	Reflow soldering	3 cycles	113	9040	0						
		MIL-STD-750-1										
	HTRB	M1038 Method A										
	High Temperature Reverse	Tj = Tjmax, $Vr = 100\%$ of max. datasheet										
# B1	Bias	reverse voltage <sup>[1]</sup>	1000 hours	116	9280	0						
	T-0	JECD33 A104										
4 4 4	TC Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000	20	2240	0						
# A4	remperature Cycling	• •	1000 cycles	28	2240	0						
	40	JESD22-A102										
	AC Autoplaye	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)				_						
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	28	2240	0						
	НЗТКВ	JESD22-A101										
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of										
# A2 alt		rated reverse voltage <sup>[1], [2]</sup>	1000 hours	28	2240	0						
AZ dIL	remperature Reverse bias		1000 Hours	28	2240	U						
	IOL	MIL-STD-750 Method 1037 ton = toff, devices powered to insure $\Delta T_j =$										
" A F	Intermittent Operating Life		1000 5	20	2220	0						
# A5	intermittent Operating Life	100 °C 101 13000 cycles	1000 hours	29	2320	0						
	RSH	JESD22-A111										
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.						
r C0	SD	200 0 - 0 0	10.5	II.a.	11.a.	II.a.						
# C10	Solderability	J-STD-002		63	630	0						
- CIU	Soluciusmicy	7 0.0 002		UJ	030	U						

<sup>[1]</sup> The physical limitations of Schottky diodes have to be considered (thermal runaway).

## **Calculation of FIT and MTTF**

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9280	0	0.46	2.19E+09

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<sup>[2]</sup> The maximum applied voltage is limited by test chamber set up and does not exceed 115V.